



Click [here](#) for the 3D model.

General Information

Series	KONNEKT Comm U2J
Style	KONNEKT
Description	SMD, MLCC, KONNEKT, Ultra-Stable, Class I
Features	High Density Packaging
RoHS	Yes
Termination	Tin
AEC-Q200	No
Chip Size	1812-3
Shelf Life	78 Weeks
MSL	1

Dimensions

L	4.5mm +/-0.3mm
W	5.3mm +/-0.6mm
T	3.2mm +/-0.3mm
B	0.6mm +/-0.35mm

Packaging Specifications

Packaging	T&R, 330mm, Plastic Tape
Packaging Quantity	2200

Specifications

Capacitance	1.4 uF
Tolerance	5%
Voltage DC	50 VDC
Dielectric Withstanding Voltage	125 VDC
Temperature Range	-55/+125°C
Temp. Coefficient	U2J
Dissipation Factor	0.1% 1 kHz 25C
Aging Rate	0.1% Loss/Decade Hour
Insulation Resistance	714.29 MOhms

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.